

MMC2114CFCAF33 :Part Detail

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General Information

Part Number	MMC2114CFCAF33
Description	MMC2114 256KFLASH 32KRAM
Product Line	GMGG2114
PTI	MBXV
Material Type	Tested Packaged Device
Life Cycle Description (code)	PRODUCT LAST SHIPMENTS
Status	No Longer Manufactured
Application/Qualification Tier	10-YEARS APPLICATION LIFE

Package Information

Package Type and Termination Count	LQFP 100
Package Description and Mechanical Drawing	LQFP 100 14*14*1.4P0.5
Device Weight(g)	0.68520
Package Material	Plastic
Mounting Style	Surface Mount
Package Length (nominal)(mm)	14.000
Package Width (nominal)(mm)	14.000
Package Thickness (nominal)(mm)	1.700
Maximum Height Above Board(mm)	1.700
Tape & Reel	No

Environmental and Compliance Information

Pb-Free	
RoHS Compliant	
Halogen Free	Yes
Material Composition Declaration (MCD)	Download MCD Report  Download MCD Report 

2nd Level Interconnect	e3
Moisture Sensitivity Level (MSL)	3
Floor Life	168 HOURS
Peak Package Body Temperature (PPT)(°C)	260
Maximum Time at Peak Temperature (s)	40
Number of Reflow Cycles	3
REACH SVHC	NXP REACH Statement
UL94 (plastics flammability test)	V0;Burning stops within 10 seconds on a vertical specimen;no drips allowed

Manufacturing Information

Micron Size(μm)	.25
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Ordering Information

Last Order Date	11 Oct 2013
Last Ship Date	11 Oct 2014
Minimum Package Quantity (MPQ)	90
MPQ Container	TRAY
Exempt from Minimum Delivery Value	Yes
Preferred Order Quantity (POQ)	450
POQ Container	BOX
Export Control Classification Number (US)	3A991A2
Harmonized Tariff (	
CCATS Document	-
ENC Status	-
Other Trade Compliance Documents	-
Budgetary Price excluding tax(US Currency	-
Device Sample Availability	24 Mar 2006
Device Production Availability	24 Mar 2006
Order	Distributor

Product/Process Change Notice (PCN)

Number	Type	Title	Issue Date	Effectivity Date
15401	Product Change Notice	0.25sgf Cu wire qualification for Freescale Kuala Lumpur 64/80-QFP & 80/100/112/144-LQFP for Non Automotive Products	30 Oct 2012	01 Apr 2013

15389A	Update Notification	END OF LIFE DUE TO LOW SALES	12 Oct 201212 Oct 2012
15389	Product Discontinuance	END OF LIFE DUE TO LOW SALES	03 Oct 201203 Oct 2012

Operating Characteristics

Ambient Operating Temperature (Min-Max) (°C)	-40 to 85
Bus Frequency (Max) (MHz)	33
External Bus Interface	MCORE External
External Memory Supported	SRAM
GPIOs	67
I/O Operating Voltage (Max) (V)	3.6
Internal Flash (KB)	256
Internal RAM (KB)	32
Power Dissipation (Max) (W) (Max) (W)	0.66
Power Dissipation (Typ) (W) (Typ) (W)	0.2
Sample Exception Availability	N
Timer Features	Realtime Interrupts Watchdog

Reliability Data Lookup

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